FDC 2214

Resonant circuit driver

Resonant circuit driver

MSP 430

Micro USB

To Computer

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Frost and ice detection

Project Title:

Designed for:

Public Release

Assembly Variant:

001

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Drawn By:

Engineer:

Richard Wang

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Version control disabled

SVN Rev:

TIDA-01465

Number:

Rev:

E1

TID #:

TIDA-01465

Orderable:

ChangeMe!

PCB Number:

PCB Rev:

Label Assembly Note

ZZ1

Not necessary for PCB labels only

ZZ2

Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3

Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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